UMB01C (QFN)

56-pin QFN package with an 8 mm × 8 mm body size, featuring a low-profile structure, exposed thermal pad, low parasitic inductance, and excellent RF and thermal performance.

1. Package Summary

Package Type Description	QFN
Package Body Material Type	Plastic
Mounting Method Type	Surface Mount
Package Size	8.0 x 8.0mm
Pin Count	56
Pin Materials	Pb free
Lead Pitch	0.5mm

2. Application

Mobile Communications
Mobile Communications Terminal, Mobile Communications Base-station
Telecommunications
Network products(LAN), Switching Transmission Cellular Base Stations

3. Feature

Package Type	Quad Flat No-Lead(QFN)
Package Size	8 mm X 8 mm
Number of Pins	56 pins
Lead Pitch	Typically 0.5 mm

Low profile and compact package
Exposed thermal pad for efficient heat dissipation
Low parasitic inductance and capacitance
Short electrical interconnection paths
Good thermal and electrical performance
Suitable for surface-mount technology(SMT)
RoHS-compliant/Pb-free package

NAMIKA

UMB01C (QFN)

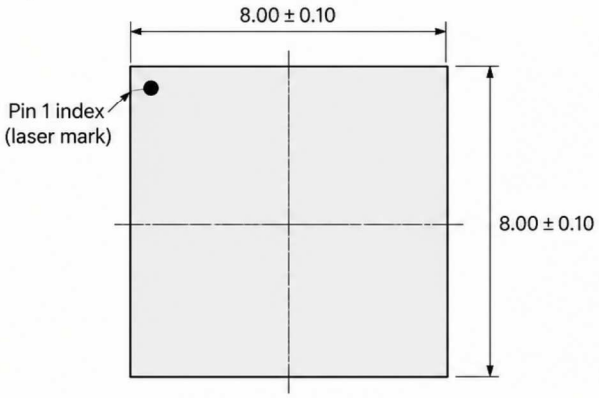
56-pin QFN package with an 8 mm × 8 mm body size, featuring a low-profile structure, exposed thermal pad, low parasitic inductance, and excellent RF and thermal performance.

4. Package Outline Dimension

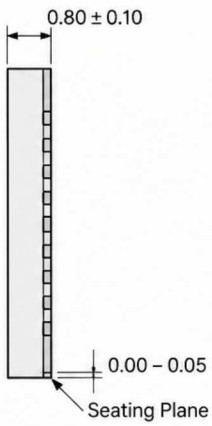
QFN 8 mm × 8 mm, 56-pin – Outline Dimension

(Typical, 0.5 mm pitch)

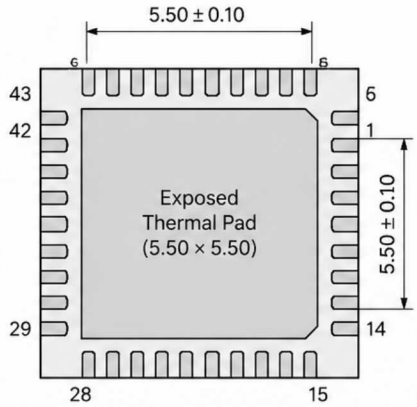
Top View



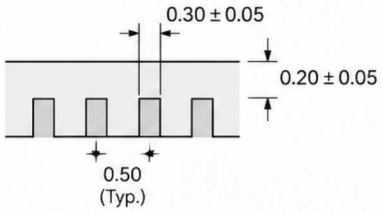
Side View



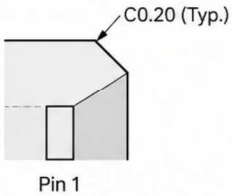
Bottom View



Detail of Terminal



Corner Detail (Pin 1)



Dimension Table (Unit: mm)

Symbol	Description	Min	Nom	Max
D	Package length	7.90	8.00	8.10
E	Package width	7.90	8.00	8.10
A	Package height	0.70	0.80	0.90
A1	Standoff	0.00	–	0.05
b	Lead width	0.25	0.30	0.35
L	Lead length	0.15	0.20	0.25
e	Lead pitch	–	0.50	–
D2	Exposed pad length	5.40	5.50	5.60
E2	Exposed pad width	5.40	5.50	5.60

Notes:
1. Dimensions are in millimeters.
2. This is a typical outline dimension for an 8 mm × 8 mm, 56-pin QFN (0.5 mm pitch).
3. The exposed thermal pad must be soldered to the PCB for proper thermal performance.
4. Exact dimensions may vary depending on the manufacturer. Refer to the specific datasheet for precise values.